



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-02-19
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6932D2.5TR	KKO7*UD34CA6	A	SHENZHEN B/E	2016-02-19
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.9, 6, 1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKO7*UD34CA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.663	mg	supplier	die	Silicon (Si)	7440-21-3		4.452	mg	954760	55663
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	6218	363
				supplier	metallization	Tungsten (W)	7440-33-7		0.046	mg	9863	575
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	1501	88
				supplier	Passivation	Silicon Oxide	7631-86-9		0.069	mg	14794	863
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	643	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	4931	288
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.034	mg	7290	425
				Leadframe	Copper & its alloys	31.953	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.015	mg	469	188
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.027	mg	845	338
Die attach	Other Organic Materials	1.236	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.125	mg	910194	14063
				supplier	glue or tape	acrylate	Proprietary		0.062	mg	50162	775
				supplier	glue or tape	Methacrylate	Proprietary		0.049	mg	39644	613
Bonding wires	Other inorganic materials	0.234	mg	supplier	wire	Gold (Au)	7440-57-5		0.234	mg	1000000	2925
Encapsulation	Other Organic Materials	41.914	mg	supplier	mold compound	Silica, vitreous	60676-86-0		36.297	mg	865987	453713
				supplier	mold compound	Epoxy Resin	25068-38-6		3.143	mg	74987	39288
				supplier	mold compound	Phenol Resin	29690-82-2		2.096	mg	50007	26200
				supplier	mold compound	Carbon black	1333-86-4		0.210	mg	5010	2625
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.168	mg	4008	2100